



# Gate Resistance Measurement and Modeling for 3D FETs

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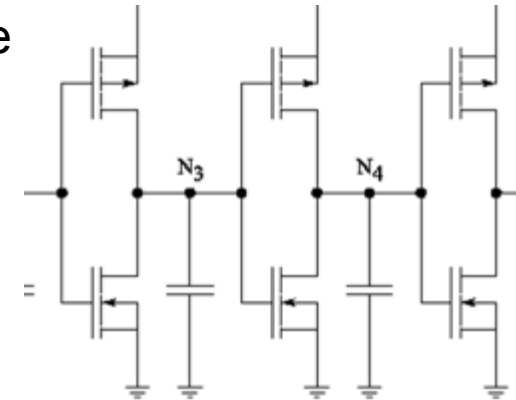


## Outline

- Who cares about gate resistance
- Gate Resistance and Capacitance in 3D FETs
- Small Signal Analysis
- $R_{gate}$  from S-parameters
- $R_{gate}$  for Modeling
- Conclusions

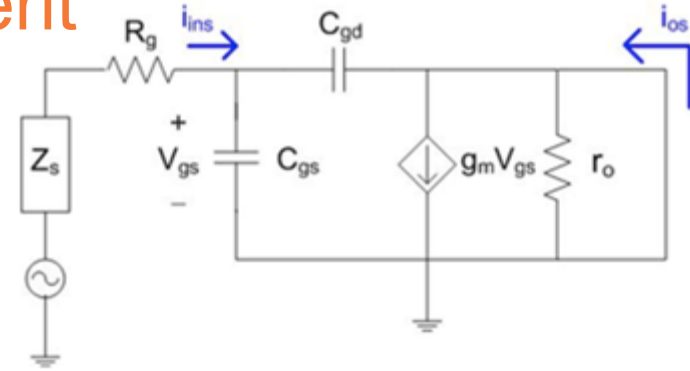
## Rgate and logic delay

- Rgate adds delays to the slewing of the gate
  - $\tau_{Rg} = R_{g} C_{gg}$
  - Important if  $\tau$  is a significant fraction of rise/fall time
- In Cmos logic 1 FET drive at least 2 gates
  - Plus some wiring
  - For fanout > 1 add more pairs of gates
  - Fanout of 3 is a typical metric
- In a fanout 3 inverter ring oscillator 1 transistor drive 6 gates
  - $\tau_{L} \approx 6 C_{gg} V_{dd} / g_{m} (V_{dd} - V_{t})$
  - Rgate can be important if it is high enough



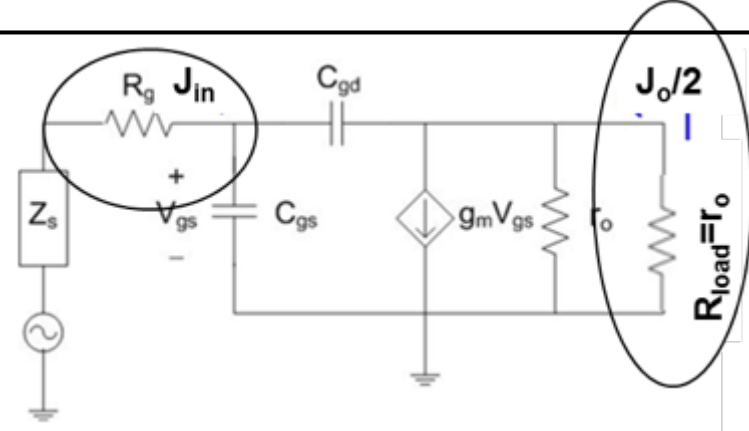
# RF performance figures of merit

- $f_{\downarrow T}$ : The frequency at which a FET has unity **current** gain
  - $R_{gate}$  does not effect current gain



$$f_T = \frac{g_m}{2\pi(C_{gs} + C_{gd}[1 + g_m(R_S + R_D)])}$$

- $f_{\downarrow MAX}$ : The frequency at which a FET has unity **power** gain
  - $R_{gate}$  Increases the input power for a given output.



- ∴ Decreases Fmax

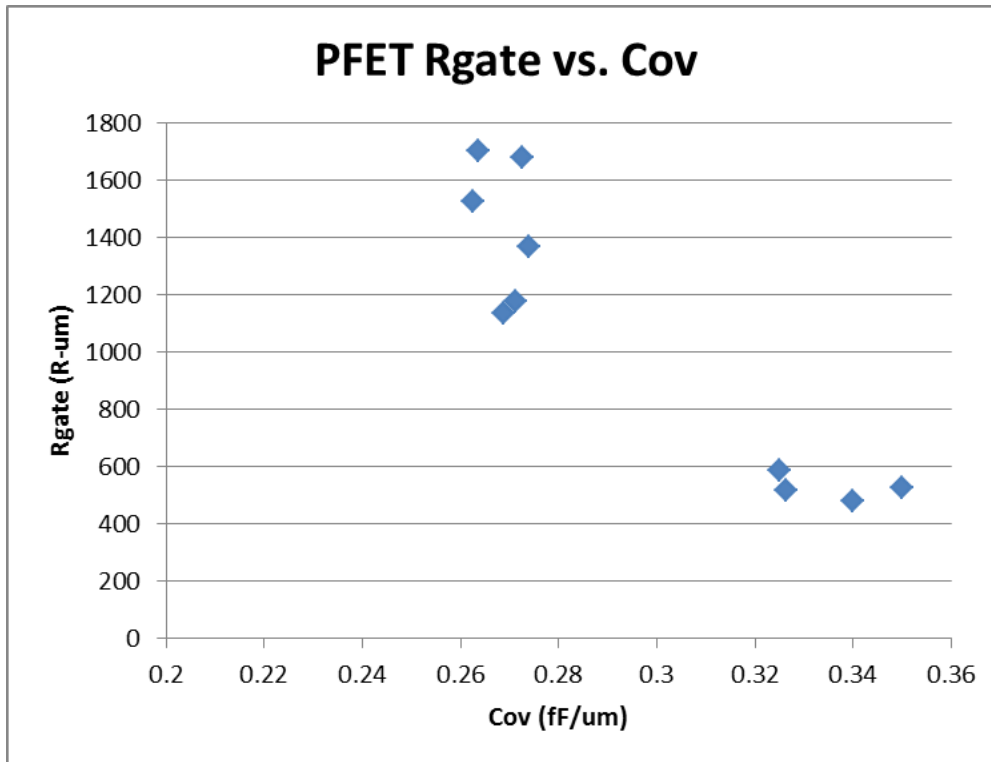
$$f_{MAX} = \frac{1}{2} \sqrt{\frac{J_T}{(C_{gs} + C_{gd}) C_{gd} (R_g + R_s) + \frac{R_g + R_s}{r_o}}}$$

## Logic vs RF sensitivity to R<sub>gate</sub>

- RF is more demanding of low R<sub>gate</sub> because the slew rates are higher
- Logic:  $\tau_L \approx 6C_{gg} V_{dd} / g_m (V_{dd} - V_t)$
- RF
  - $\tau_{ft} \approx C_{gg} / g_m$
  - RF is at 5-10 times as sensitive as Logic to R<sub>gate</sub>
  - RF devices are typically wider, increasing R<sub>gate</sub>

# Gate Resistance and Capacitance in 3D FET

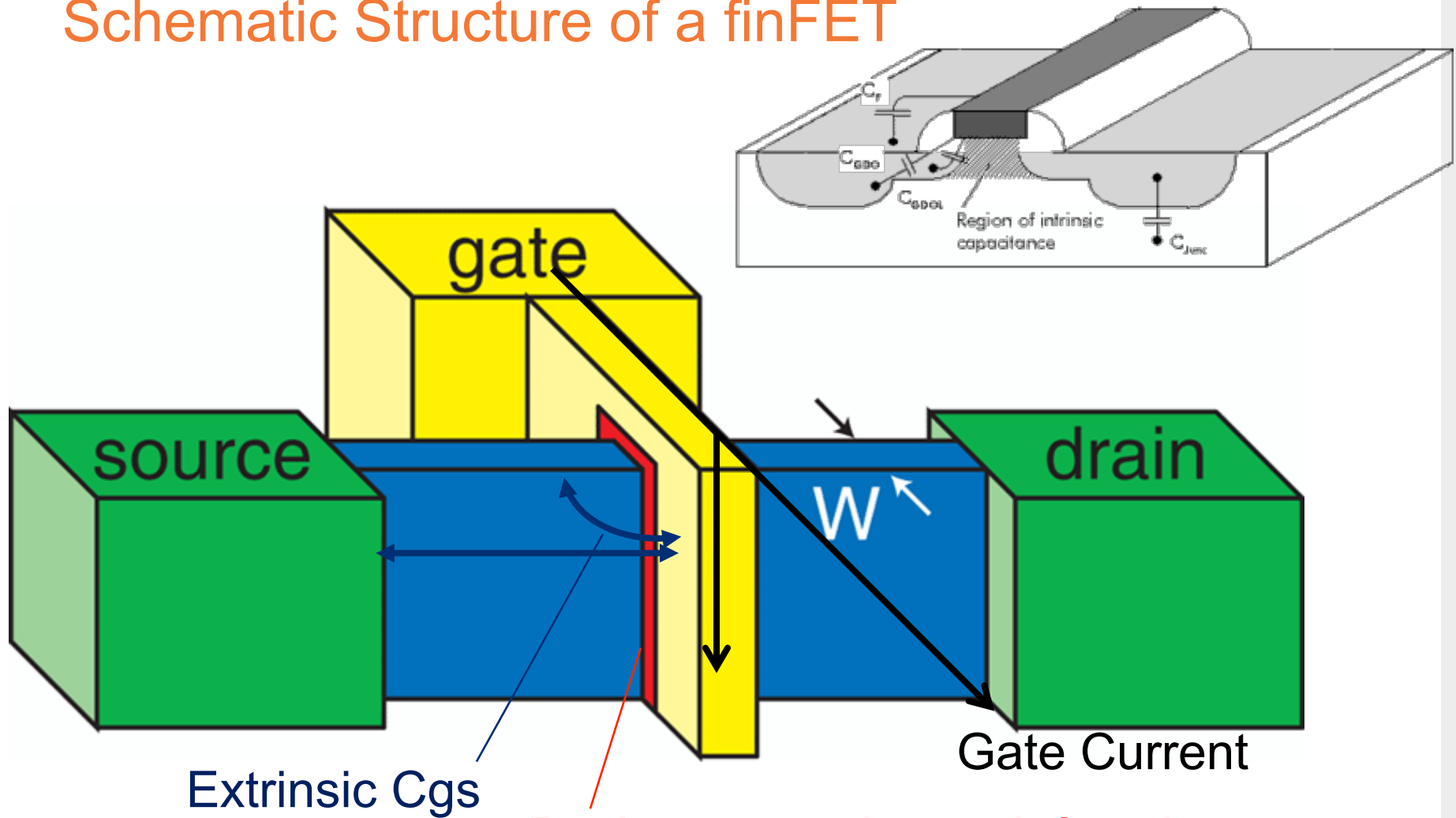
## A surprise result



- A process change significantly increased PFET Cov—expected
- PFET R<sub>gate</sub> dropped
  - $R_g = \text{Re}[1/Y_{11}]$
- Physically R<sub>gate</sub> should not change
- NFET R<sub>gate</sub> did not change (same physical structure, no change to NFET Cov)

# R<sub>gate</sub> & C<sub>gg</sub> in 3D FETs

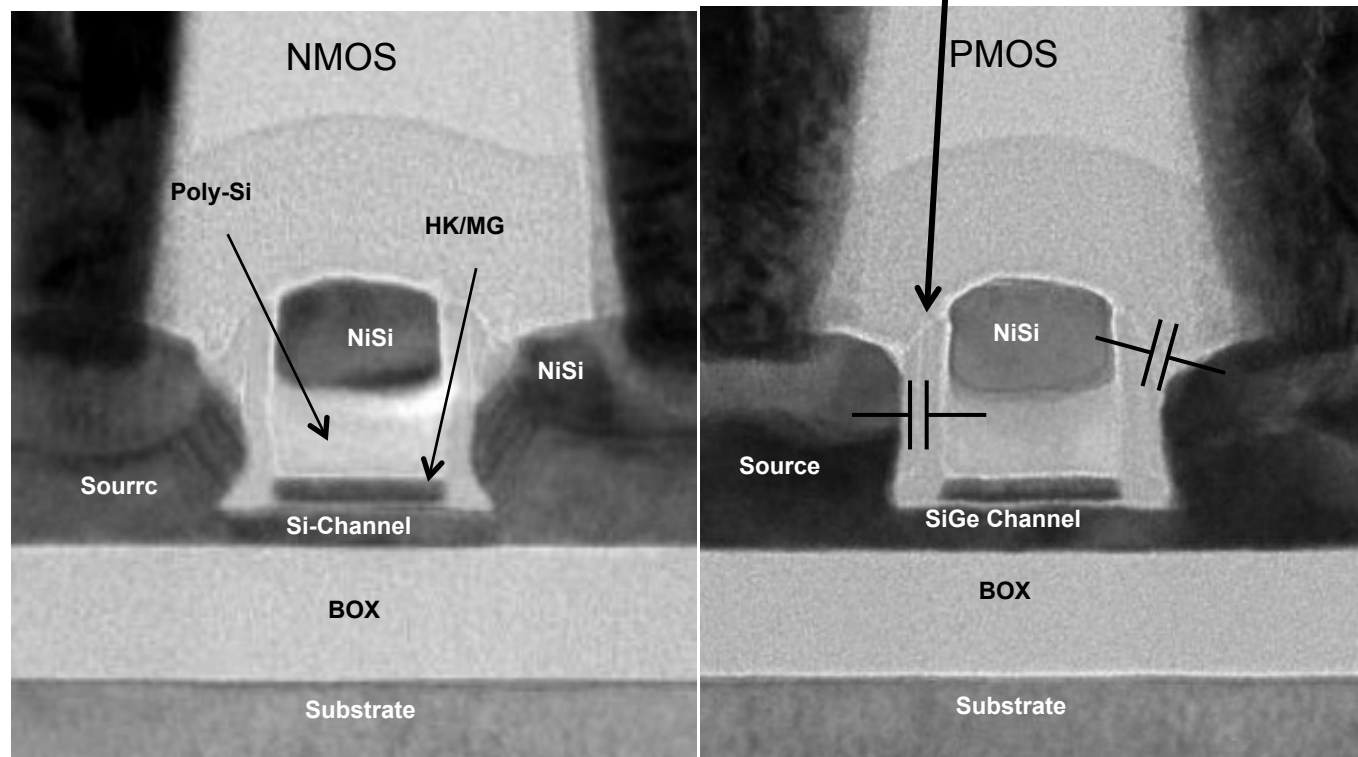
## Schematic Structure of a finFET



Resistance at the work function metal interface and Intrinsic C<sub>gs</sub>

# FDSOI with Raised Source Drains

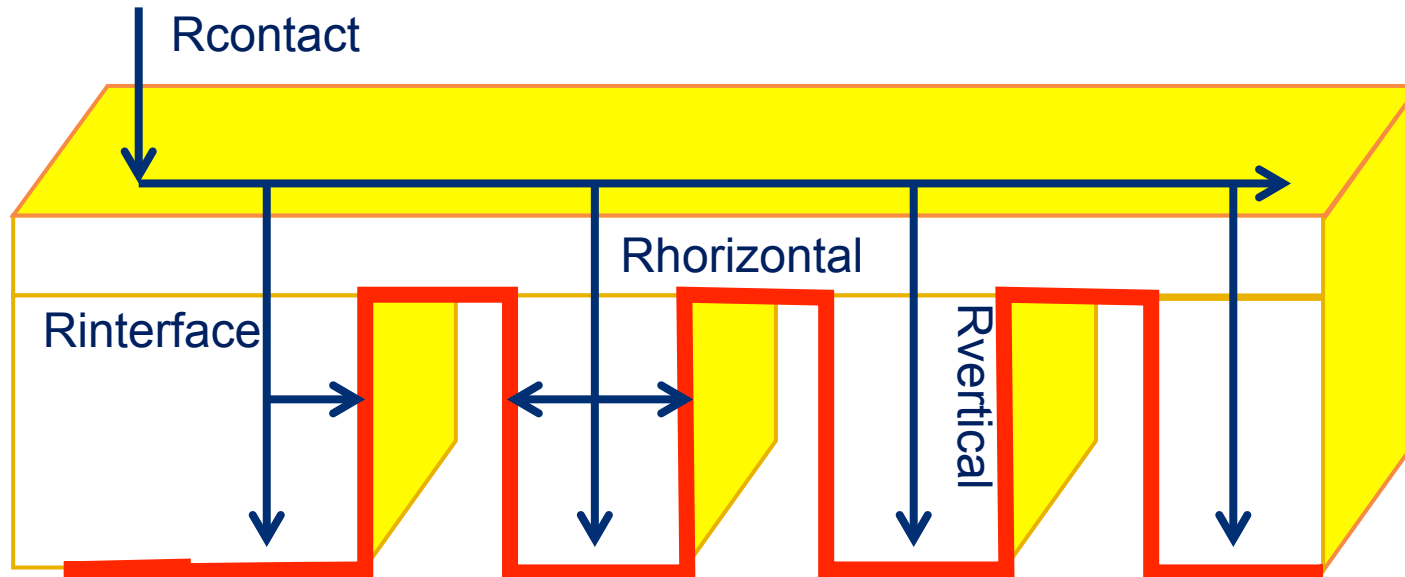
- Large capacitance above the work function metal





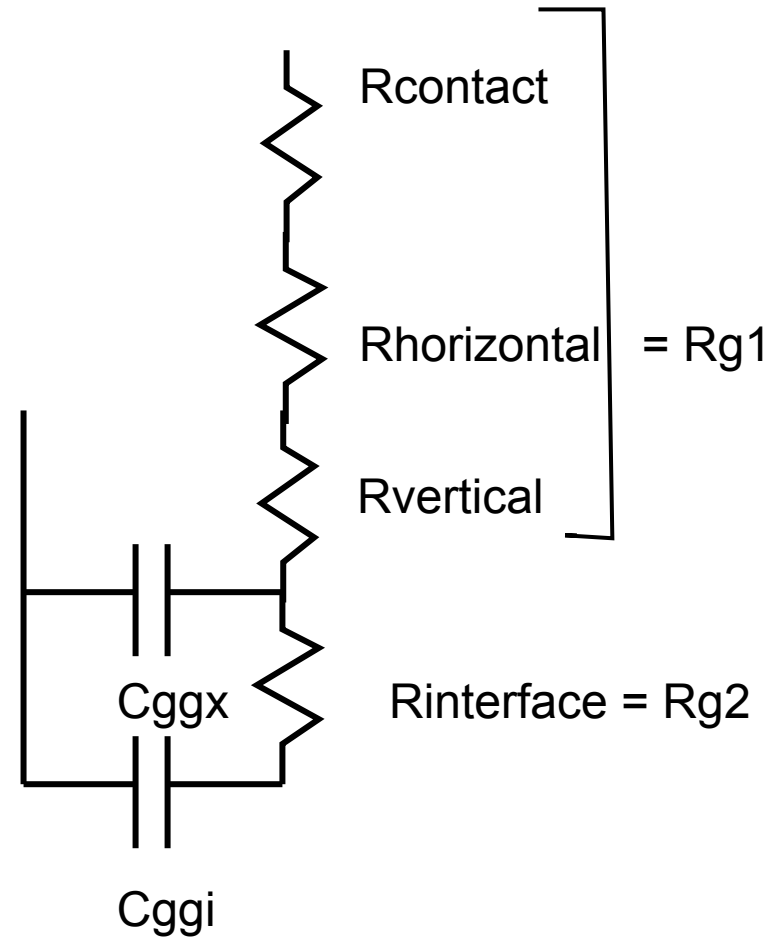
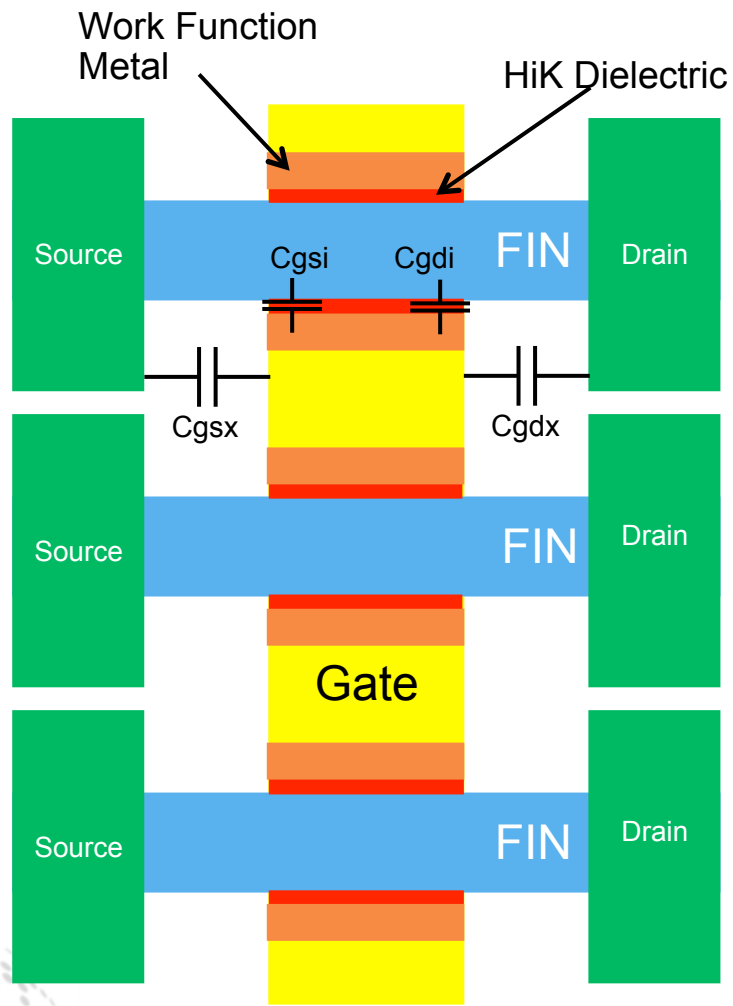
# Normalized Gate Resistance Scaling

$R_{\text{gate}}$  is normalized as  $R_g \cdot N_{\text{fin}} \cdot W_{\text{fin}}$  so that  $R_g \cdot C_{\text{gg}}$  is  $W$  independent



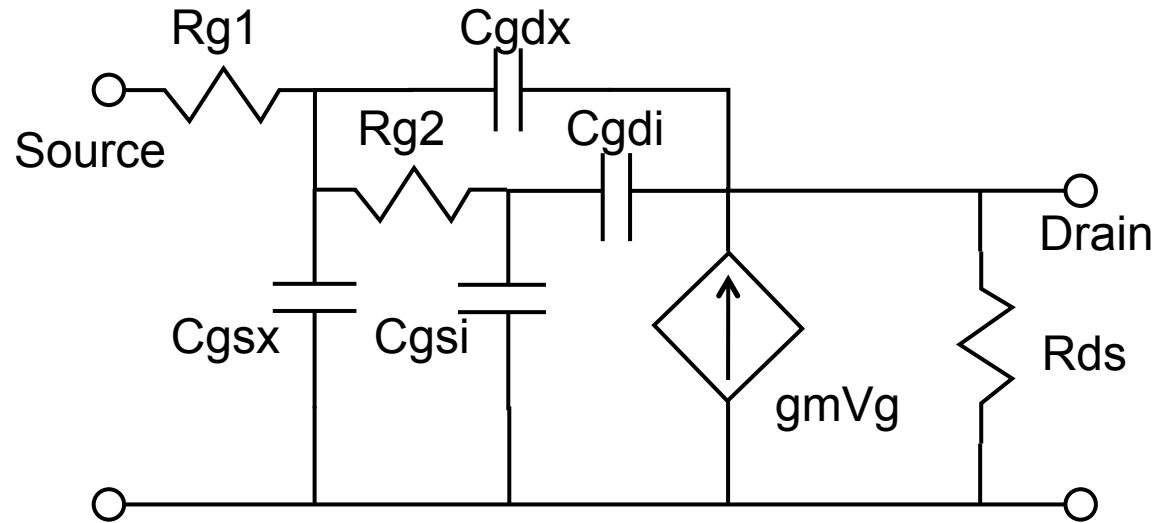
- Normalized  $R_{\text{contact}}$  scales as  $W$
- Normalized  $R_{\text{horizontal}}$  scales as  $W^2$
- Normalized  $R_{\text{vertical}}$  and  $R_{\text{interface}}$  do not scale with  $W$

# Top view, Crosssection through fin

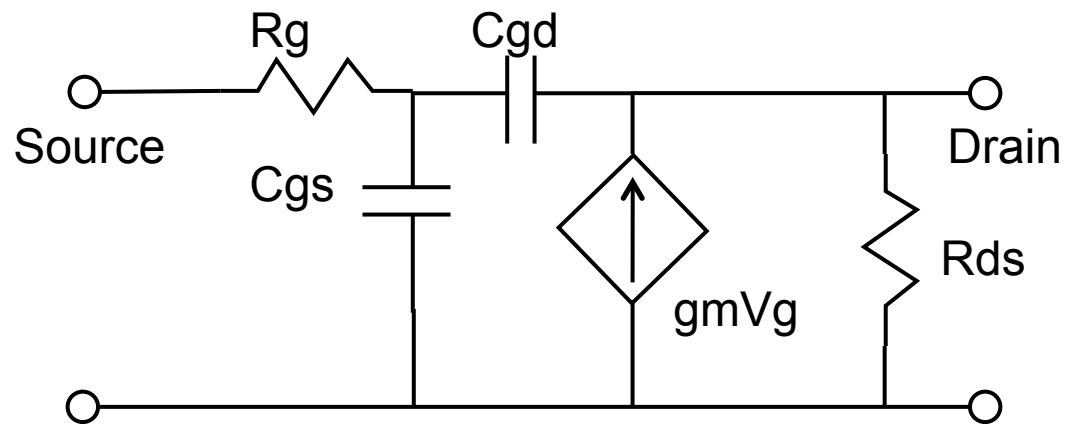


## 3-D FET small signal model

Approximate the distributed RC by a Pi-network



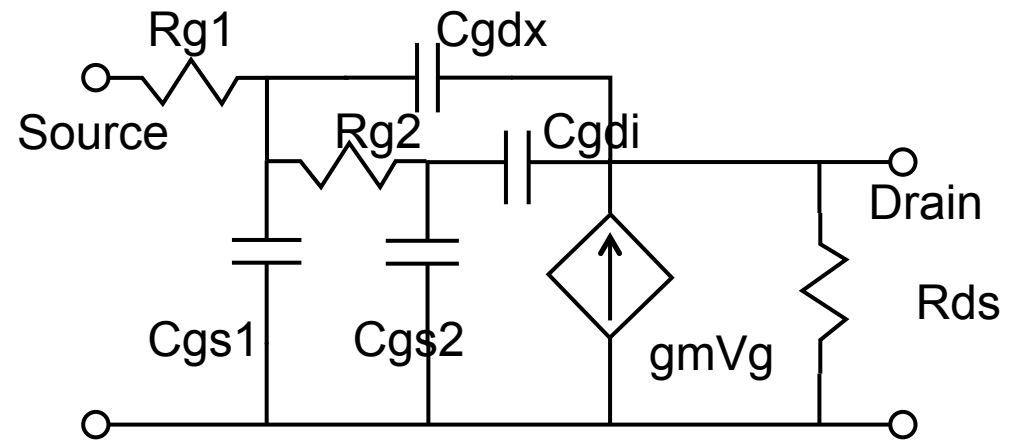
Looking for the equivalent  $R_g$  for the standard topology



## Common definitions of $R_g$ for measurement

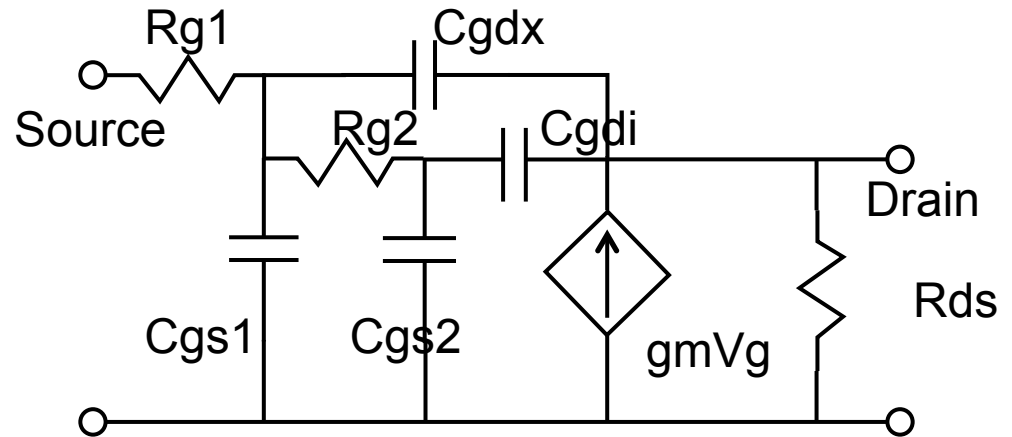
- $R_g = \text{Re}[1/Y_{11}]$  : Real part of the impedance “looking into the gate”
- $R_g = \text{Re}[Y_{12}]/(\text{Im}[Y_{11}]*\text{Im}[Y_{12}])$  : “looking into the drain”
- $Y_{11} = I_{\downarrow 1} / V_{\downarrow 1}$  with  $V_{\downarrow 2} = 0$
- $Y_{12} = I_{\downarrow 1} / V_{\downarrow 2}$  with  $V_{\downarrow 1} = 0$
- Use the fact that  $R_{\downarrow g} \ll 1/\omega C_{\downarrow gg}$
- Because  $R_g$  is so small the effective gate capacitance is unchanged by the resistor network:
- $C_{\downarrow gg} = (C_{\downarrow ggi} + C_{\downarrow ggx})$ ;  $C_{\downarrow gd} = (C_{\downarrow gdi} + C_{\downarrow gdx})$ ;  $C_{\downarrow gs} = (C_{\downarrow gsi} + C_{\downarrow gsx})$

## 3-D Gate Resistance



- $Y_{11} = \omega^2 C_{ggi} (C_{ggx} R_{g1} + C_{ggi} R_{g2}) + j\omega C_{gg}$
- $Y_{12} = \omega^2 (C_{gd} C_{gg} R_{g1} + C_{gd}^2 C_{gg2} R_{g2}) + j\omega C_{gd}$
- $R_{\downarrow g} = \text{Re}[1/Y_{11}] = R_{g1} + R_{g2} (C_{ggi} / C_{ggx} + C_{ggi})^2$
- $R_{\downarrow g}' = \text{Re}[Y_{12}] / \text{Im}[Y_{12}] \text{Im}[Y_{11}] = R_{g1} + R_{g2} C_{gdi} C_{ggi} / (C_{gdi} + C_{gd})(C_{ggi} + C_{ggx})$
- $\text{Re}[Y_{12}] / \text{Im}[Y_{12}] > \text{Re}[Y_{11}] / \text{Im}[Y_{11}]$  therefore  $R_{g'}$  gives a better measurement
- $R_g$  (looking into gate) is always  $> R_{g'}$  looking into drain
- Typical data for our PFET shows  $R_g/R_{g'} \sim 1.5-2.0$

## Modeling the 3-D gate resistance



- Adding the extra node gives physically correct model for  $R_{gate}$  looking into both gate and the drain.
- $R_{gate}$  is most important for its impact on input power
- Output power is determined by  $R_{ds}$  and output circuit impedance
- For operation in common source circuits can drop the extra node with little impact on accuracy
- Gate resistor should be the resistor given by  $Re[1/Y_{11}]$
- In practice we tune resistor to match power gain ( $f_{MAX}$ )

## Conclusions:

- 3-D gate makes measured  $R_{gate}$  a function of the distribution of capacitances between extrinsic and intrinsic regions
- $R_{gate}$  looking into gate and looking into drain are different
- Can simulation with a single effective  $R_{gate}$
- $R_{gate}$  looking into drain gives a more repeatable measurement
- $R_{gate}$  looking into the gate give correct power simulation

